IGBT - Inverter Welding

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Trench construction, and provides superior performance in demanding switching applications, offering both low on state voltage and minimal switching loss. The IGBT is well suited for welding applications. Incorporated into the device is a soft and fast co–packaged free wheeling diode with a low forward voltage.

Features

- $T_{Jmax} = 175^{\circ}C$
- Soft Fast Reverse Recovery Diode
- Optimized for High Speed Switching
- 10 µs Short Circuit Capability
- These are Pb-Free Devices

Typical Applications

Welding

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage	V _{CES}	1200	V
Collector current @ Tc = 25°C @ Tc = 100°C	I _C	50 25	A
Pulsed collector current, T _{pulse} limited by T _{Jmax}	I _{CM}	100	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	l _F	50 25	A
Diode pulsed current, T _{pulse} limited by T _{Jmax}	I _{FM}	100	Α
Gate-emitter voltage Transient gate-emitter voltage $(T_{pulse} = 5 \mu s, D < 0.10)$	$V_{\sf GE}$	±20 ±30	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P _D	385 192	W
Short Circuit Withstand Time V _{GE} = 15 V, V _{CE} = 500 V, T _J ≤ 150°C	T _{SC}	10	μs
Operating junction temperature range	TJ	–55 to +175	°C
Storage temperature range	T _{stg}	-55 to +175	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T _{SLD}	260	°C

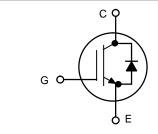
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

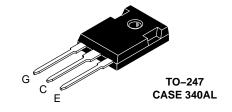


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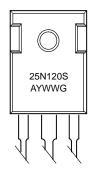
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25 A, 1200 V V_{CEsat} = 2.0 V E_{off} = 0.60 mJ





MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTB25N120SWG	TO-247 (Pb-Free)	30 Units / Rail

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction–to–case, for IGBT	$R_{\theta JC}$	0.39	°C/W
Thermal resistance junction-to-case, for Diode	$R_{\theta JC}$	0.63	°C/W
Thermal resistance junction–to–ambient	$R_{\theta JA}$	40	°C/W

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC	•				•	-
Collector–emitter breakdown voltage, gate–emitter short–circuited	$V_{GE} = 0 \text{ V}, I_{C} = 500 \mu\text{A}$	V _{(BR)CES}	1200	_	-	V
Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 25 A V _{GE} = 15 V, I _C = 25 A, T _J = 175°C	V _{CEsat}	- -	2.00 2.40	2.40 -	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 400 \mu A$	$V_{GE(th)}$	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	V _{GE} = 0 V, V _{CE} = 1200 V V _{GE} = 0 V, V _{CE} = 1200 V, T _{J =} 175°C	I _{CES}	_ _	_ _	0.4 2	mA
Gate leakage current, collector-emitter short-circuited	V _{GE} = 20 V , V _{CE} = 0 V	I _{GES}	-	-	200	nA
Input capacitance		C _{ies}	_	4420	_	pF
Output capacitance	$V_{CE} = 20 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$ $V_{CE} = 600 \text{ V}, I_{C} = 25 \text{ A}, V_{GE} = 15 \text{ V}$ $TIVE \ LOAD$ $T_{J} = 25^{\circ}C$ $V_{CC} = 600 \text{ V}, I_{C} = 25 \text{ A}$ $R_{g} = 10 \Omega$ $V_{GE} = 0 \text{ V} / 15 \text{ V}$	C _{oes}	_	151	_	
Reverse transfer capacitance		C _{res}	_	81	_	
Gate charge total		Q_g	_	178	-	nC
Gate to emitter charge	$V_{CE} = 600 \text{ V}, I_{C} = 25 \text{ A}, V_{GE} = 15 \text{ V}$	Q _{ge}	_	39	-	
Gate to collector charge		Q _{gc}	_	83	_	
SWITCHING CHARACTERISTIC, INDUC	TIVE LOAD					
Turn-on delay time		t _{d(on)}	_	87	_	ns
Rise time	- Т _Ј = 25°С	t _r	_	74	-	
Turn-off delay time		t _{d(off)}	_	179	-	
Fall time	$V_{CC} = 600 \text{ V}, I_{C} = 25 \text{ A}$ $R_{c} = 10 \Omega$	t _f	_	136	-	
Turn-on switching loss	V _{GE} = 0 V/ 15V	E _{on}	_	1.95	_	mJ
Turn-off switching loss	$V_{CC} = 600 \text{ V}, I_{C} = 25 \text{ A}$	E _{off}	_	0.60	_	
Total switching loss		E _{ts}	_	2.55	_	
Turn-on delay time		t _{d(on)}	_	84	_	ns
Rise time	1	t _r	_	94	_	
Turn-off delay time	T _J = 150°C	t _{d(off)}	_	185	_	
Fall time	$V_{CC} = 600 \text{ V}, I_{C} = 25 \text{ A}$ $R_{q} = 10 \Omega$	t _f	_	245	_	
Turn-on switching loss	V _{GE} = 0 V/ 15V	E _{on}	_	2.39	_	mJ
Turn-off switching loss	1	E _{off}	-	1.26	_	
Total switching loss	1	E _{ts}	_	3.65	_	
DIODE CHARACTERISTIC						
Forward voltage	$V_{GE} = 0 \text{ V, } I_F = 25 \text{ A}$ $V_{GE} = 0 \text{ V, } I_F = 50 \text{ A, } T_J = 175^{\circ}\text{C}$	V _F	- -	2.10 2.30	2.60 -	V
Reverse recovery time	T _J = 25°C	t _{rr}	-	154	_	ns
Reverse recovery charge	$I_F = 25 \text{ Å}, V_R = 400 \text{ V}$ $di_F/dt = 200 \text{ A/}\mu\text{s}$	Q _{rr}	-	1.3	_	μC
Reverse recovery current	1	I _{rrm}	_	15	_	Α

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

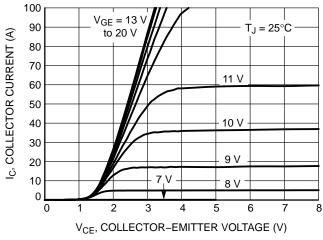


Figure 1. Output Characteristics

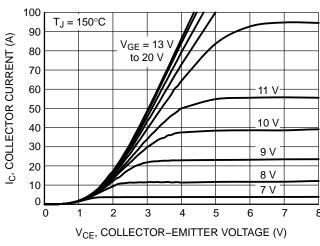


Figure 2. Output Characteristics

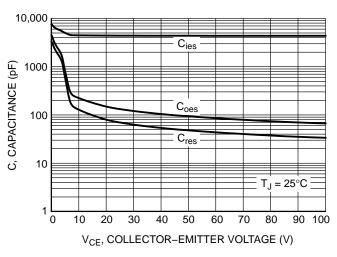


Figure 3. Typical Capacitance

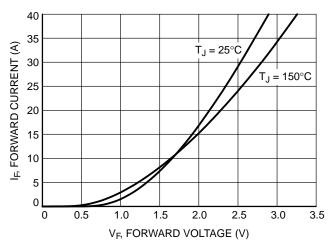


Figure 4. Diode Forward Characteristics

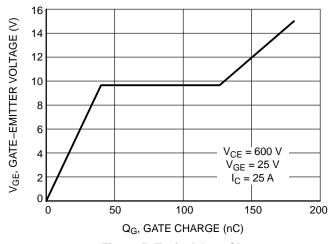


Figure 5. Typical Gate Charge

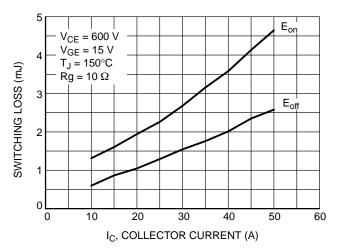
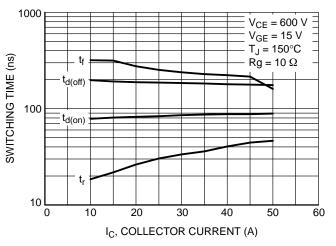


Figure 6. Switching Loss vs. I_C

TYPICAL CHARACTERISTICS



1000 IC, COLLECTOR CURRENT (A) 100 10 dc operation 100 μs Single Nonrepetitive Pulse $T_C = 25^{\circ}C$ Curves must be derated 1 ms linearly with increase in temperature 0.1 10 100 10k V_{CE}, COLLECTOR-EMITTER VOLTAGE (V)

Figure 7. Switching Time vs. I_C

Figure 8. Safe Operating Area

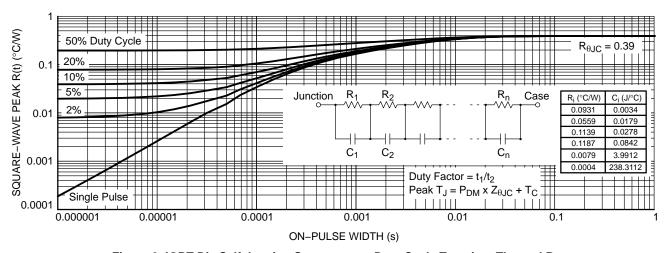


Figure 9. IGBT Die Self-heating Square-wave Duty Cycle Transient Thermal Response

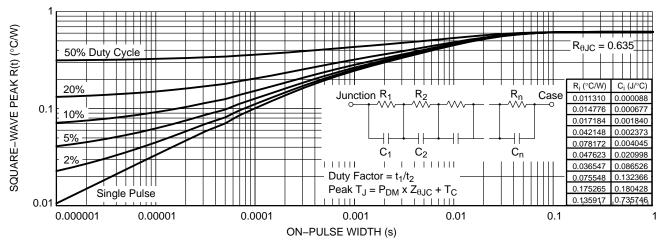
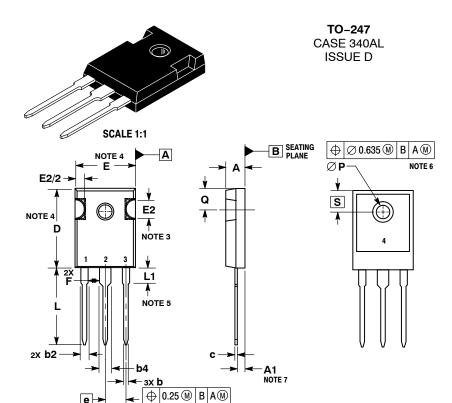


Figure 10. Diode Die Self-heating Square-wave Duty Cycle Transient Thermal Response

e -



DATE 17 MAR 2017

- NOTES:

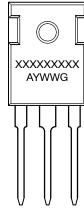
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. SLOT REQUIRED, NOTCH MAY BE ROUNDED.

 - DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH.
 MOLD FLASH SHALL NOT EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY
- LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY
- ©P SHALL HAVE A MAXIMUM DRAFT ANGLE OF 1.5° TO THE TOP OF THE PART WITH A MAXIMUM DIAMETER OF 3.91.

 DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED

	MILLIMETERS		
DIM	MIN	MAX	
Α	4.70	5.30	
A1	2.20	2.60	
b	1.07	1.33	
b2	1.65	2.35	
b4	2.60	3.40	
С	0.45	0.68	
D	20.80	21.34	
Е	15.50	16.25	
E2	4.32	5.49	
е	5.45 BSC		
F	2.655		
L	19.80	20.80	
L1	3.81	4.32	
P	3.55	3.65	
Q	5.40	6.20	
S	6.15 BSC		

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code Α = Assembly Location

Υ = Year WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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 IGW08T120FKSA1
 IGW75N60H3FKSA1
 HGTG40N60B3
 FGH60N60SMD_F085

 FGH75T65UPD
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